

We claim:

1 1. A layer sequence built on a substrate in thin-layer technology, said layer
2 sequence comprising an electrically conductive sputtered layer (4) and an
3 electrically conductive reinforcing layer (5) for reinforcing or strengthening the
4 sputtered layer, said reinforcing layer (5) being applied by a method other than
5 sputtering, wherein said electrically conductive reinforcing layer (5) is made a less
6 effective reinforcing means for the sputtered layer in regions (6,10,14, 16, 17, 19)
7 of said electrically conductive sputtered layer (4) to be adjusted than in other
8 regions outside of said regions to be adjusted.

1 2. The layer sequence as defined in claim 1, wherein said electrically conductive
2 reinforcing layer (5) is thinner in said regions (6,10,14, 16, 17, 19) of said
3 electrically conductive sputtered layer (4) to be adjusted than in said other regions.

1 3. The layer sequence as defined in claim 1, wherein said electrically conductive
2 sputtered layer (4) is made of gold.

1 4. The layer sequence as defined in claim 1, wherein said electrically conductive
2 reinforcing layer (5) is made of gold.

1 5. The layer sequence as defined in claim 1, wherein said regions (14, 16, 17) of
2 said electrically conductive sputtered layer (4) to be adjusted are located in
3 portions of the layer sequence carrying less current than other portions.

1 6. The layer sequence as defined in claim 5, wherein at least one of said regions
2 (14, 16, 17) of said electrically conductive sputtered layer (4) to be adjusted is
3 located at an end of an open conducting line (13).

1 7. The layer sequence as defined in claim 2, wherein said other regions outside of
2 said regions (14, 16, 17) of said electrically conductive sputtered layer (4) to be
3 adjusted include contacting surfaces (11,12).

1 8. The layer sequence as defined in claim 1, wherein said regions (14, 16, 17) of
2 said electrically conductive sputtered layer (4) to be adjusted are located on a side
3 of said sputtered layer (4) opposite from said substrate (1).

1 9. A layer sequence built on a substrate in thin-layer technology, said layer
2 sequence comprising an electrically conductive sputtered layer (4) and an
3 electrically conductive reinforcing layer (5) for reinforcing or strengthening the
4 sputtered layer, said reinforcing layer (5) being applied by a method other than
5 sputtering, wherein said electrically conductive reinforcing layer (5) has a smaller
6 thickness in regions (6,10,14, 16, 17, 19) of said electrically conductive sputtered
7 layer (4) to be adjusted than in other regions outside of said regions to be adjusted.

1 10. The layer sequence as defined in claim 9, wherein said electrically conductive
2 reinforcing layer (5) is eliminated from said regions (6,10,14, 16, 17, 19) of said
3 electrically conductive sputtered layer (4) to be adjusted.

1 11. The layer sequence as defined in claim 9, wherein said sputtered layer (4) and
2 said reinforcing layer (5) are both made of gold.